Features

- Fast Read Access Time 70 ns
- 5-Volt-Only Reprogramming
- Page Program Operation

Single Cycle Reprogram (Erase and Program)
Internal Address and Data Latches for 64-Bytes

- Internal Program Control and Timer
- Hardware and Software Data Protection
- Fast Program Cycle Times

Page (64-Byte) Program Time - 10 ms

Chip Erase Time - 10 ms

- DATA Polling for End of Program Detection
- Low Power Dissipation

50 mA Active Current

300 μA CMOS Standby Current

- Typical Endurance > 10,000 Cycles
- Single 5V ± 10% Supply
- CMOS and TTL Compatible Inputs and Outputs
- Commercial and Industrial Temperature Ranges

Description

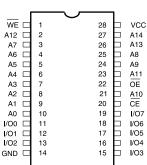
The AT29C256 is a 5-volt-only in-system Flash programmable and erasable read only memory (PEROM). Its 256K of memory is organized as 32,768 words by 8 bits. Manufactured with Atmel's advanced nonvolatile CMOS technology, the device offers access times to 70 ns with power dissipation of just 275 mW. When the device is deselected, the CMOS standby current is less than 300 μ A. The device endurance is such that any sector can typically be written to in excess of 10,000 times.

(continued)

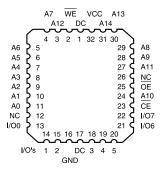
Pin Configurations

Pin Name	Function
A0 - A14	Addresses
CE	Chip Enable
ŌE	Output Enable
WE	Write Enable
I/O0 - I/O7	Data Inputs/Outputs
NC	No Connect
DC	Don't Connect

DIP Top View



PLCC Top View



Note: PLCC package pins 1 and 17 are DON'T CONNECT.

TSOP Top View

				Type 1					
OE .	🗐		22		21		Þ		A10
A9 A1		23	24		19	20	Ĕ	CE	I/O7
A13 A	·8 🖯	25	26		17	18	Б	I/O6	I/O5
/CC _	14点	27	28		15	16	k	I/O4	I/O3
W	屉】	1				14	Ē	GND	1/03
A12 A	7 🗒	3	2		13	12	Ĕ	I/O1	
Α6 Δ	,5 🖥	5	4		11	10	В	A0	I/O0
A4	 	7	6		9	8	Ė	A2	Α1
	\J -L_	•					\vdash	,	

256K (32K x 8) 5-volt Only CMOS Flash Memory

0046L



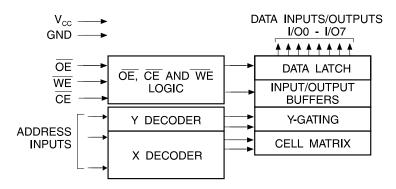


Description (Continued)

To allow for simple in-system reprogrammability, the AT29C256 does not require high input voltages for programming. Five-volt-only commands determine the operation of the device. Reading data out of the device is similar to reading from a static RAM. Reprogramming the AT29C256 is performed on a page basis; 64-bytes of data are loaded into the device and then simultaneously programmed. The contents of the entire device may be erased by using a 6-byte software code (although erasure before programming is not needed).

During a reprogram cycle, the address locations and 64-bytes of data are internally latched, freeing the address and data bus for other operations. Following the initiation of a program cycle, the device will automatically erase the page and then program the latched data using an internal control timer. The end of a program cycle can be detected by DATA polling of I/O7. Once the end of a program cycle has been detected a new access for a read, program or chip erase can begin.

Block Diagram



Device Operation

READ: The AT29C256 is accessed like a static RAM. When CE and OE are low and WE is high, the data stored at the memory location determined by the address pins is asserted on the outputs. The outputs are put in the high impedance state whenever CE or OE is high. This dual-line control gives designers flexibility in preventing bus contention.

BYTE LOAD: A byte load is performed by applying a low pulse on the WE or CE input with CE or WE low (respectively) and OE high. The address is latched on the falling edge of CE or WE, whichever occurs last. The data is latched by the first rising edge of CE or WE. Byte loads are used to enter the 64-bytes of a page to be programmed or the software codes for data protection and chip erasure.

PROGRAM: The device is reprogrammed on a page basis. If a byte of data within a page is to be changed, data for the entire page must be loaded into the device. Any byte that is not loaded during the programming of its page will be indeterminate. Once the bytes of a page are loaded into the device, they are simultaneously programmed during the internal programming period. After the first data byte has been loaded into the device, successive bytes are entered in the same manner. Each new byte to be programmed must have its high to low transition on $\overline{\text{WE}}$ (or $\overline{\text{CE}}$) within 150 μs of the low to high transition is not detected within 150 μs of the last low to high transition, the

load period will end and the internal programming period will start. A6 to A14 specify the page address. The page address must be valid during each high to low transition of WE (or $\overline{\text{CE}}$). A0 to A5 specify the byte address within the page. The bytes may be loaded in any order; sequential loading is not required. Once a programming operation has been initiated, and for the duration of t_{WC} , a read operation will effectively be a polling operation.

SOFTWARE DATA PROTECTION: A software controlled data protection feature is available on the AT29C256. Once the software protection is enabled a software algorithm must be issued to the device before a program may be performed. The software protection feature may be enabled or disabled by the user; when shipped from Atmel, the software data protection feature is disabled. To enable the software data protection, a series of three program commands to specific addresses with specific data must be performed. After the software data protection is enabled the same three program commands must begin each program cycle in order for the programs to occur. All software program commands must obey the page program timing specifications. Once set, the software data protection feature remains active unless its disable command is issued. Power transitions will not reset the software data protection feature, however the software feature will guard against inadvertent program cycles during power transitions.

(continued)

Device Operation (Continued)

Once set, software data protection will remain active unless the disable command sequence is issued.

After setting SDP, any attempt to write to the device without the 3-byte command sequence will start the internal write timers. No data will be written to the device; however, for the duration of t_{WC} , a read operation will effectively be a polling operation.

After the software data protection's 3-byte command code is given, a byte load is performed by applying a low pulse on the WE or CE input with CE or WE low (respectively) and OE high. The address is latched on the falling edge of CE or WE, whichever occurs last. The data is latched by the first rising edge of CE or WE. The 64-bytes of data must be loaded into each sector by the same procedure as outlined in the program section under device operation.

HARDWARE DATA PROTECTION: Hardware features protect against inadvertent programs to the AT29C256 in the following ways: (a) V_{CC} sense— if V_{CC} is below 3.8V (typical), the program function is inhibited. (b) V_{CC} power on delay— once V_{CC} has reached the V_{CC} sense level, the device will automatically time out 5 ms (typical) before programming. (c) Program inhibit— holding any one of OE low, CE high or WE high inhibits program cycles. (d) Noise

filter— pulses of less than 15 ns (typical) on the $\overline{\text{WE}}$ or $\overline{\text{CE}}$ inputs will not initiate a program cycle.

PRODUCT IDENTIFICATION: The product identification mode identifies the device and manufacturer and may be accessed by a hardware operation. For details, see Operating Modes or Product Identification.

DATA POLLING: The AT29C256 features DATA polling to indicate the end of a program cycle. During a program cycle an attempted read of the last byte loaded will result in the complement of the loaded data on I/O7. Once the program cycle has been completed, true data is valid on all outputs and the next cycle may begin. DATA polling may begin at any time during the program cycle.

TOGGLE BIT: In addition to DATA polling the AT29C256 provides another method for determining the end of a program or erase cycle. During a program or erase operation, successive attempts to read data from the device will result in I/O6 toggling between one and zero. Once the program cycle has completed, I/O6 will stop toggling and valid data will be read. Examining the toggle bit may begin at any time during a program cycle.

OPTIONAL CHIP ERASE MODE: The entire device can be erased by using a 6-byte software code. Please see Software Chip Erase application note for details.

Absolute Maximum Ratings*

Temperature Under Bias55°C to +12	25°C
Storage Temperature65°C to +15	50°C
All Input Voltages (including NC Pins) with Respect to Ground0.6V to +6	.25V
All Output Voltages with Respect to Ground0.6V to V _{CC} +	0.6V
Voltage on OE with Respect to Ground0.6V to +1	3.5V

*NOTICE: Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.





DC and AC Operating Range

		AT29C256-70	AT29C256-90	AT29C256-12	AT29C256-15
Operating	Com.	0°C - 70°C	0°C - 70°C	0°C - 70°C	0°C - 70°C
Temperature (Case)	Ind.	-40°C - 85°C	-40°C - 85°C	-40°C - 85°C	-40°C - 85°C
V _{CC} Power Supply		5V ± 5%	$5V \pm 10\%$	$5V \pm 10\%$	5V ± 10%

Operating Modes

Mode	CE	ŌE	WE	Ai	I/O
Read	VIL	VIL	ViH	Ai	Dout
Program (2)	VIL	ViH	V_{IL}	Ai	DIN
5V Chip Erase	VIL	ViH	V_{IL}	Ai	
Standby/Write Inhibit	ViH	X ⁽¹⁾	Χ	Χ	High Z
Write Inhibit	Χ	Χ	VIH		
Write Inhibit	Χ	VIL	Χ		
Output Disable	Χ	VIH	Χ		High Z
High Voltage Chip Erase	VIL	VH (3)	VIL	Χ	High Z
Product Identification					
Hardwara	V	V	ViH	$A1 - A14 = V_{IL}, A9 = V_{H},$ $A0 = V_{IL}$	Manufacturer Code (4)
Hardware	VIL	V _{IL} V _{IL}		$A1 - A14 = V_{IL}, A9 = V_{H},$ $A0 = V_{IH}$	Device Code ⁽⁴⁾
Software ⁽⁵⁾				A0 = V _{IL}	Manufacturer Code (4)
Sullware (9)				A0 = V _{IH}	Device Code ⁽⁴⁾

Notes: 1. X can be V_{IL} or V_{IH} .

2. Refer to AC Programming Waveforms.

3. $V_H = 12.0V \pm 0.5V$.

- 4. Manufacturer Code: 1F, Device Code: DC
- 5. See details under Software Product Identification Entry/Exit.

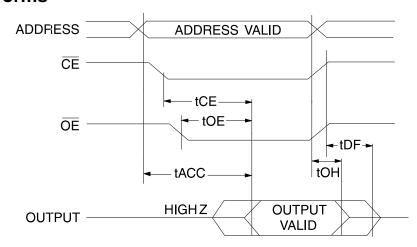
DC Characteristics

Symbol	Parameter	Condition	Min	Max	Units
ILI	Input Load Current	V _{IN} = 0V to V _C C		10	μΑ
ILO	Output Leakage Current	$V_{I/O} = 0V$ to V_{CC}		10	μΑ
I _{SB1}	V _{CC} Standby Current CMOS	$\overline{\text{CE}} = V_{\text{CC}} - 0.3V \text{ to } V_{\text{CC}}$		300	μΑ
I _{SB2}	V _{CC} Standby Current TTL	CE = 2.0V to V _{CC}		3	mA
Icc	V _{CC} Active Current	$f = 5 MHz; I_{OUT} = 0 mA$		50	mA
VIL	Input Low Voltage			0.8	\
VIH	Input High Voltage		2.0		\
VoL	Output Low Voltage	I _{OL} = 2.1 mA		.45	\
V _{OH1}	Output High Voltage	I _{OH} = -400 μA	2.4		V
V _{OH2}	Output High Voltage CMOS	$I_{OH} = -100 \mu A; V_{CC} = 4.5 V$	4.2		V

AC Read Characteristics

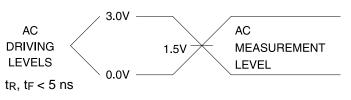
		AT290	256-70	AT29C256-90		AT29C256-12		AT29C256-15		
Symbol	Parameter	Min	Max	Min	Max	Min	Max	Min	Max	Units
tACC	Address to Output Delay		70		90		120		150	ns
t _{CE} ⁽¹⁾	CE to Output Delay		70		90		120		150	ns
toE (2)	OE to Output Delay	0	40	0	40	0	50	0	70	ns
t _{DF} (3, 4)	CE or OE to Output Float	0	25	0	25	0	30	0	40	ns
tон	Output Hold from OE, CE or Address, whichever occurred first	0		0		0		0		ns

AC Read Waveforms (1, 2, 3, 4)

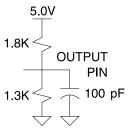


- Notes: 1. $\overline{\text{CE}}$ may be delayed up to t_{ACC} t_{CE} after the address transition without impact on t_{ACC} .
 - 2. $\overline{\text{OE}}$ may be delayed up to t_{CE} t_{OE} after the falling edge of $\overline{\text{CE}}$ without impact on t_{CE} or by t_{ACC} t_{OE} after an address change without impact on t_{ACC} .
- 3. t_{DF} is specified from \overline{OE} or \overline{CE} whichever occurs first $(C_L = 5 \text{ pF})$.
- 4. This parameter is characterized and is not 100% tested.

Input Test Waveforms and Measurement Level



Output Test Load



Pin Capacitance (f = 1 MHz, T = 25°C) $^{(1)}$

	Тур	Max	Units	Conditions
C _{IN}	4	6	pF	$V_{IN} = 0V$
Соит	8	12	pF	Vout = 0V

Note: 1. This parameter is characterized and is not 100% tested.



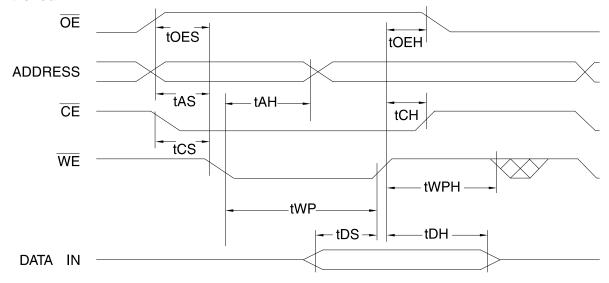


AC Byte Load Characteristics

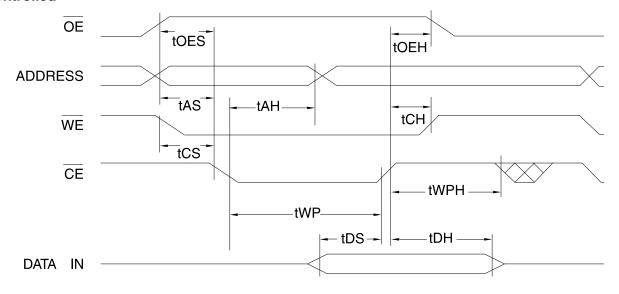
Symbol	Parameter	Min	Max	Units
tas, toes	Address, OE Set-up Time	0		ns
tah	Address Hold Time	50		ns
tcs	Chip Select Set-up Time	0		ns
tch	Chip Select Hold Time	0		ns
twp	Write Pulse Width (WE or CE)	90		ns
t _{DS}	Data Set-up Time	35		ns
tDH, tOEH	Data, OE Hold Time	0		ns
twph	Write Pulse Width High	100		ns

AC Byte Load Waveforms

WE Controlled



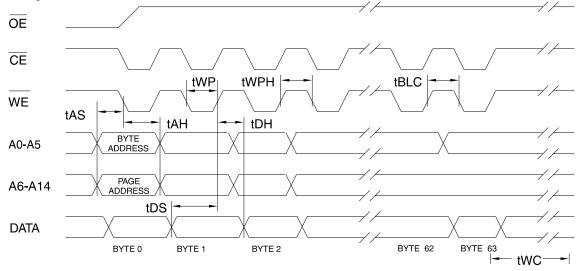
CE Controlled



Program Cycle Characteristics

Symbol	Parameter	Min	Max	Units
twc	Write Cycle Time		10	ms
tas	Address Set-up Time	0		ns
t _{AH}	Address Hold Time	50		ns
t _{DS}	Data Set-up Time	35		ns
tDH	Data Hold Time	0		ns
twp	Write Pulse Width	90		ns
tBLC	Byte Load Cycle Time		150	μs
twpH	Write Pulse Width High	100		ns

Program Cycle Waveforms (1, 2, 3)

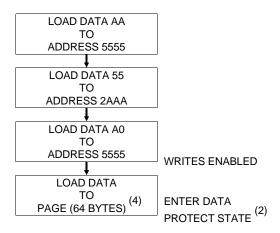


Notes: 1. A6 through A14 must specify the page address during each high to low transition of WE (or CE).

- 2. $\overline{\text{OE}}$ must be high when $\overline{\text{WE}}$ and $\overline{\text{CE}}$ are both low.
- 3. All bytes that are not loaded within the page being programmed will be indeterminate.



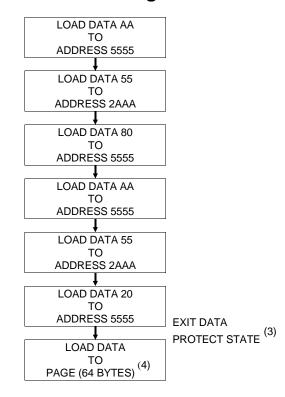
Software Data Protection Enable Algorithm (1)



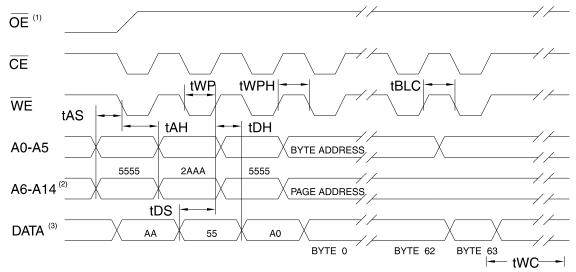
Notes for software program code:

- Data Format: I/O7 I/O0 (Hex);
 Address Format: A14 A0 (Hex).
- 2. Data Protect state will be activated at end of program cycle.
- Data Protect state will be deactivated at end of program period.
- 4. 64-bytes of data must be loaded.

Software Data Protection Disable Algorithm (1)



Software Protected Program Cycle Waveform (1, 2, 3)



- Notes: 1. A6 through A14 must specify the page address during each high to low transition of WE (or CE) after the software code has been entered.
- 2. \overline{OE} must be high when \overline{WE} and \overline{CE} are both low.
- 3. All bytes that are not loaded within the page being programmed will be indeterminate.

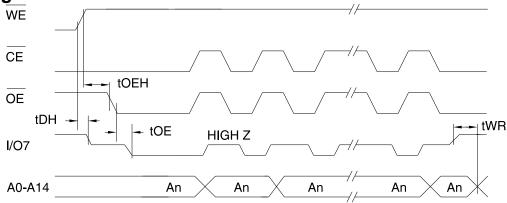
Data Polling Characteristics (1)

Symbol	Parameter	Min	Тур	Max	Units
tDH	Data Hold Time	0			ns
toeh	OE Hold Time	10			ns
toe	OE to Output Delay (2)				ns
twR	Write Recovery Time	0			ns

Notes: 1. These parameters are characterized and not 100% tested.

2. See toE spec in AC Read Characteristics.

Data Polling Waveforms



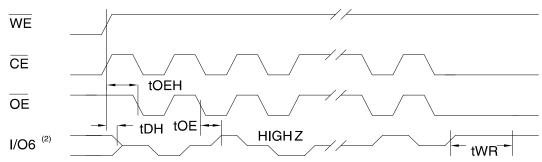
Toggle Bit Characteristics (1)

Symbol	Parameter	Min	Тур	Max	Units
tDH	Data Hold Time	0			ns
toeh	OE Hold Time	10			ns
toe	OE to Output Delay (2)				ns
toehp	OE High Pulse	150			ns
t _{WR}	Write Recovery Time	0			ns

Notes: 1. These parameters are characterized and not 100% tested.

2. See toe spec in AC Read Characteristics.

Toggle Bit Waveforms (1, 2, 3)



Notes: 1. Toggling either \overline{OE} or \overline{CE} or both \overline{OE} and \overline{CE} will operate toggle bit.

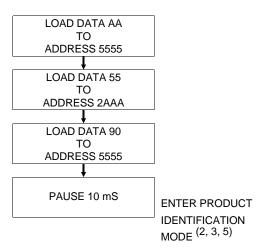
2. Beginning and ending state of I/O6 will vary.

3. Any address location may be used but the address should not vary.





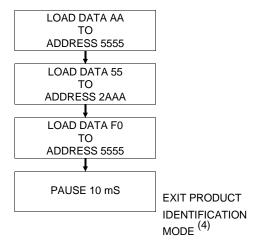
Software Product Identification Entry (1)

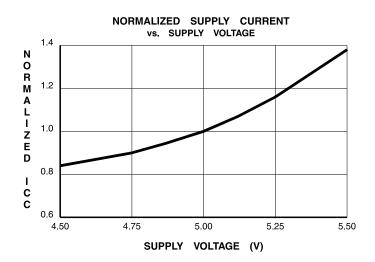


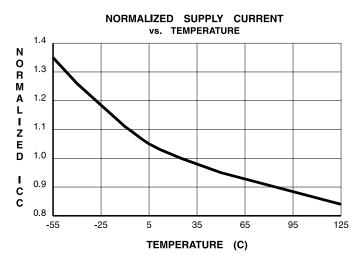
Notes for software product identification:

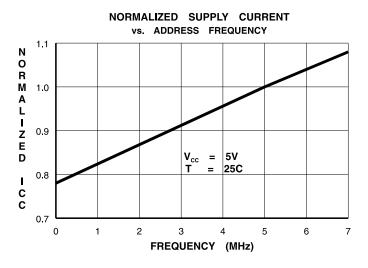
- Data Format: I/O7 I/O0 (Hex);
 Address Format: A14 A0 (Hex).
- A1 A14 = V_{IL}.
 Manufacture Code is read for A0 = V_{IL};
 Device Code is read for A0 = V_{IH}.
- 3. The device does not remain in identification mode if powered down.
- 4. The device returns to standard operation mode.
- 5. Manufacturer Code: 1F Device Code: DC

Software Product (1) Identification Exit











Ordering Information

t _{ACC} (ns)	I _{CC} (mA)				
	Active	Standby	Ordering Code	Package	Operation Range
70	50	0.3	AT29C256-70JC AT29C256-70PC AT29C256-70TC	32J 28P6 28T	Commercial (0° to 70°C)
	50	0.3	AT29C256-70JI AT29C256-70TI	32J 28T	Industrial (-40° to 85°C)
90	50	0.3	AT29C256-90JC AT29C256-90PC AT29C256-90TC	32J 28P6 28T	Commercial (0° to 70°C)
	50	0.3	AT29C256-90JI AT29C256-90PI AT29C256-90TI	32J 28P6 28T	Industrial (-40° to 85°C)
120	50	0.3	AT29C256-12JC AT29C256-12PC AT29C256-12TC	32J 28P6 28T	Commercial (0° to 70°C)
	50	0.3	AT29C256-12JI AT29C256-12PI AT29C256-12TI	32J 28P6 28T	Industrial (-40° to 85°C)
150	50	0.3	AT29C256-15JC AT29C256-15PC AT29C256-15TC	32J 28P6 28T	Commercial (0° to 70°C)
	50	0.3	AT29C256-15JI AT29C256-15PI AT29C256-15TI	32J 28P6 28T	Industrial (-40° to 85°C)

Package Type				
32J	32 Lead, Plastic J-Leaded Chip Carrier (PLCC)			
28P6	28 Lead, 0.600" Wide, Plastic Dual Inline Package (PDIP)			
28T	28 Lead, Thin Small Outline Package (TSOP)			